

SMD-Terminal block Pico with push wire contacts and contact opening function

without insulating housing

1 pole - 46.110.1001.48

Funnel-shaped wire insertion channel for easy wire insertion

Direct insertion of solid and stranded, tinned wire ends and finely stranded conductors by using the contact opening function

Contact opening function - also for release of already inserted wires

Mounting and wiring position: PCB top side

Machine-compatible "tape-and-reel" packaging

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: CrNi / CuSn
Clamping spring material: CrNi
Contact material: CuSn
Contact surface: hot-dipped tinned

Note: Terminal without insulation housing!
Protection against contact when using voltage > extra-low voltage (SELV, PELV) must be ensured in the application.


Footprint Rast 6.5 mm (630 V)


Footprint eng Rast 3.0 mm


Packaging data 46.110.1001.48	
Weight per piece	0.15 g
Pieces per coil	6.000 pcs
Reel diameter	330 mm - 13"
Reel width	16 mm
Weight per reel	1.3 kg
Number of reels per cardboard	18 pcs
Number of SMD terminal blocks per cardboard	108.000 pcs
Weight per cardboard	22.5 kg
Cardboard dimensions (LxWxH)	400 x 355 x 365 mm


LED-SMD LINE


U_{imp}
4 kV










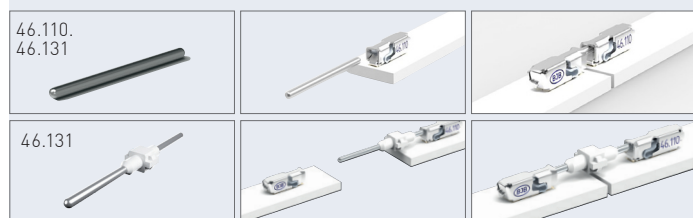




CAD

Accessories:

SMD Pico-B2B-connector. For connection of LED modules.



Tool for contact opening

To open contacts for use of finely stranded wires or for release of already inserted wires.



46.110.U801.89

Connection data	
Connection technology	Push wire contacts
Solid wires	0.20 - 0.75 mm ² , AWG 24-18
Stranded, tinned wires	0.20 - 0.5 mm ² , AWG 24-20
Stranded wires	0.20 - 0.75 mm ² , AWG 24-18
Strip length (ø < 1.55 mm) with IMS Boards / IMS PCBs	6.5 - 7.5 mm
Strip length	7.5 - 9.5 mm
Conductor entry angle to PCB	0°
Wire release function by	Contact opening tool
Pull-out force according to DN 60999-1	
0.2 mm ²	min. 10 N
0.34 mm ²	min. 15 N
0.5 mm ²	min. 20 N
0.75 mm ²	min. 30 N
Insertion force	max. 10 N

Geometrical data	
Pin spacing	6.5 mm / 0.16 inch
Width	2.3 mm / 0.15 inch
Height	2.7 mm / 0.16 inch
Depth	8 mm / 0.52 inch

Material data	
Insulating material group	-
Insulating material	-
PTI	-
Flammability class, based on UL 94	-
Clamping spring material	CrNi
Contact material	CuSn
Contact surface	hot-dipped tinned

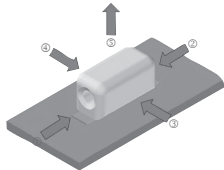
Mechanical data	
Mounting position	PCB top side
Mounting type	Lead-free reflow soldering

Temperature data	
Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 122 °C

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1). The data are based on the exemplary grid dimension of 6.5 mm.	
Rated voltage (III / 3)	320 V
Rated impulse voltage (III / 3)	4 kV
Rated voltage (III / 2)	320 V
Rated impulse voltage (III / 2)	4 kV
Rated voltage (II / 2)	630 V
Rated impulse voltage (II / 2)	4 kV
Rated current	9 A

Rated data according to UL 1977 / CSA-C22.2 No. 182.3	
Rated voltage	630 V
Rated current	USR: 9 A, AWG 24 - 18
	CNR: 6 A, AWG 24 20
	CNR: 9 A, AWG 18

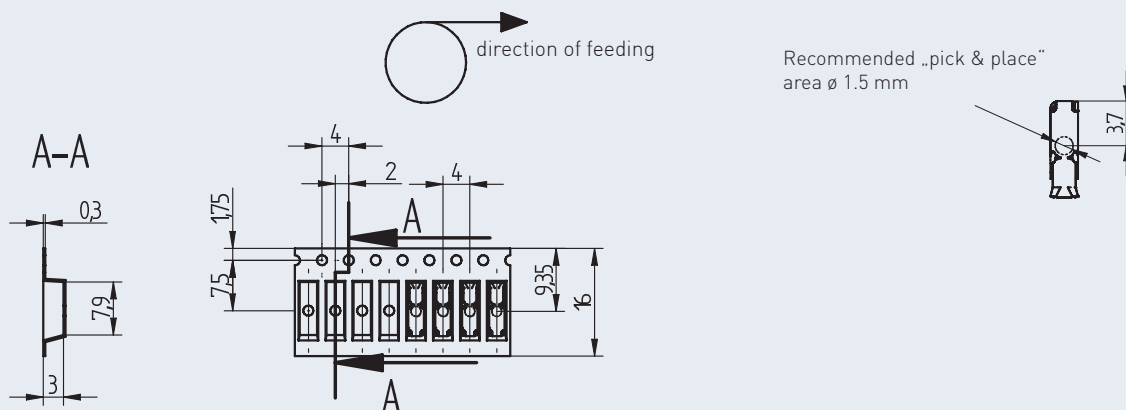
Country specific certificates	
VDE / ENEC	EN IEC 606947-7-4: 2019-10, EN IEC 60947-7-4:2019 File no.: 40053886
cURus	UL 1977 / CSA-C22.2 No. 182.3, File no.: E-365006

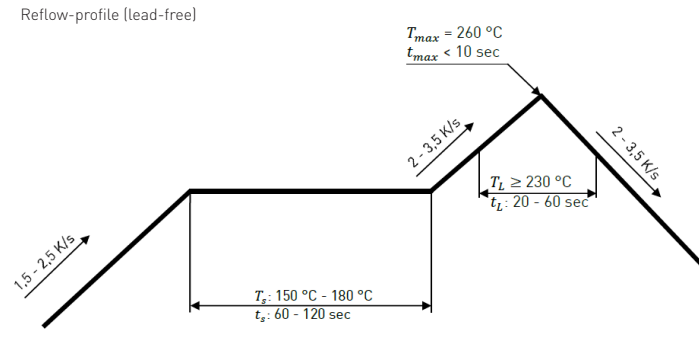
Shear forces according to IEC 62137-1-2.	
<p>These values are maximum values that apply only for impuls, not for continuous load.</p> 	
Direction 1 shear force along	50 N
Direction 2 shear force along	50 N
Direction 3 shear force across	30 N
Direction 4 shear force across	30 N
Direction 5 pull-off force	30 N

Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C. Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	<p>Reflow-profile (lead-free)</p> 
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150 µm)